



Material Content Data Sheet



Sales Product Name	SAK-XC2238N-40F80L AA			Issued		29. August 2013		
MA#	MA001031242							
Package	PG-LQFP-64-6			Weight*		372.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.688	7.70	7.70	77025	77025
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		87	
	non noble metal	zinc	7440-66-6	0.130	0.03		349	
	non noble metal	iron	7439-89-6	2.600	0.70		6980	
	non noble metal	copper	7440-50-8	105.558	28.34	29.08	283417	290833
wire	noble metal	gold	7440-57-5	1.862	0.50	0.50	4999	4999
encapsulation	organic material	carbon black	1333-86-4	1.096	0.29		2943	
	plastics	epoxy resin	-	29.600	7.95		79474	
	inorganic material	silicondioxide	60676-86-0	188.562	50.64	58.88	506278	588695
leadfinish	non noble metal	tin	7440-31-5	4.066	1.09	1.09	10916	10916
plating	noble metal	silver	7440-22-4	1.611	0.43	0.43	4325	4325
glue	plastics	epoxy resin	-	2.161	0.58		5802	
	noble metal	silver	7440-22-4	6.482	1.74	2.32	17405	23207
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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